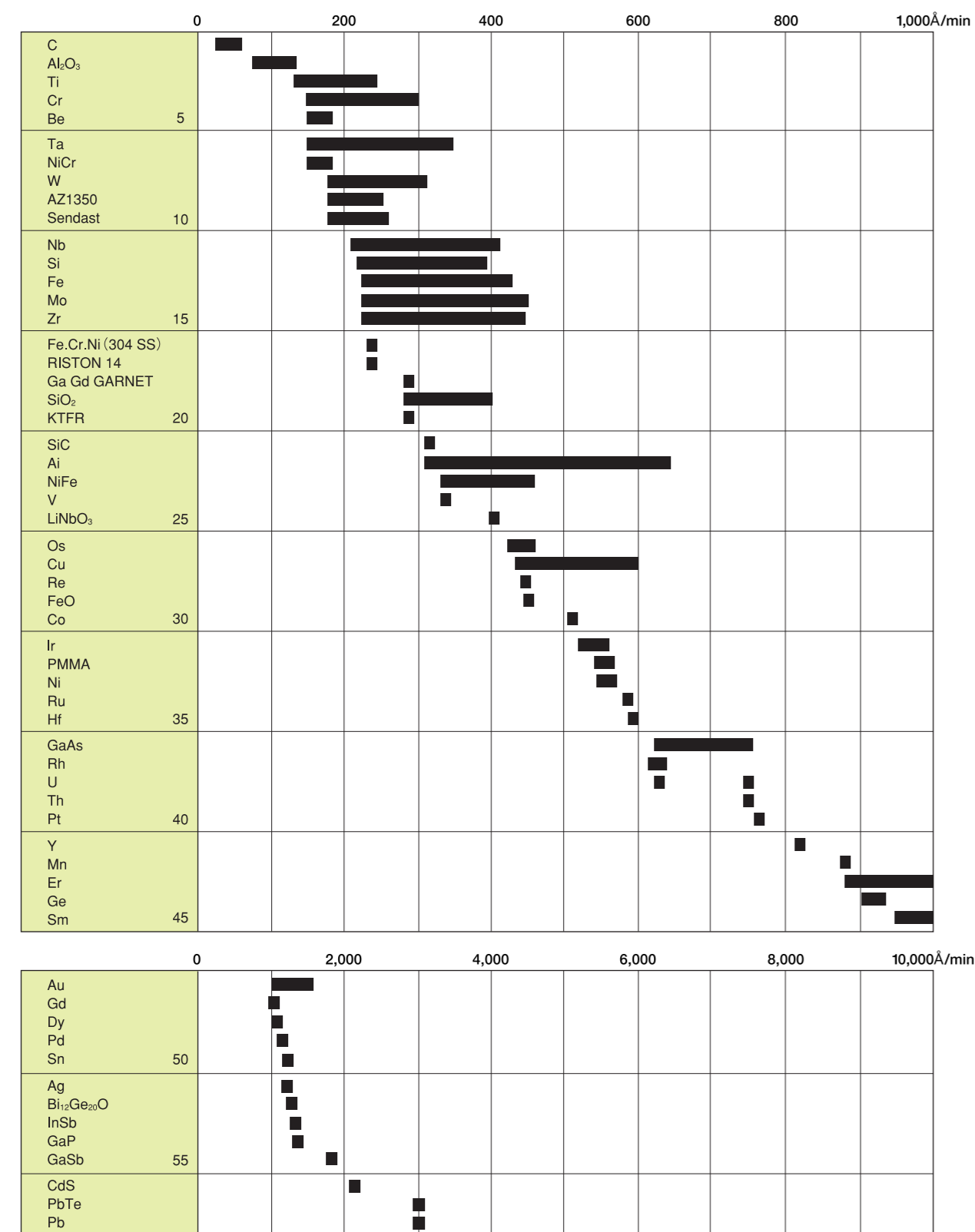


milling rate

This table shows reference milling rate in Å/min for elements and compounds.
 Gas : Ar, Beam Voltage : 500V, Incident Angle : 0 degree, Ion current density : 1mA/cm²

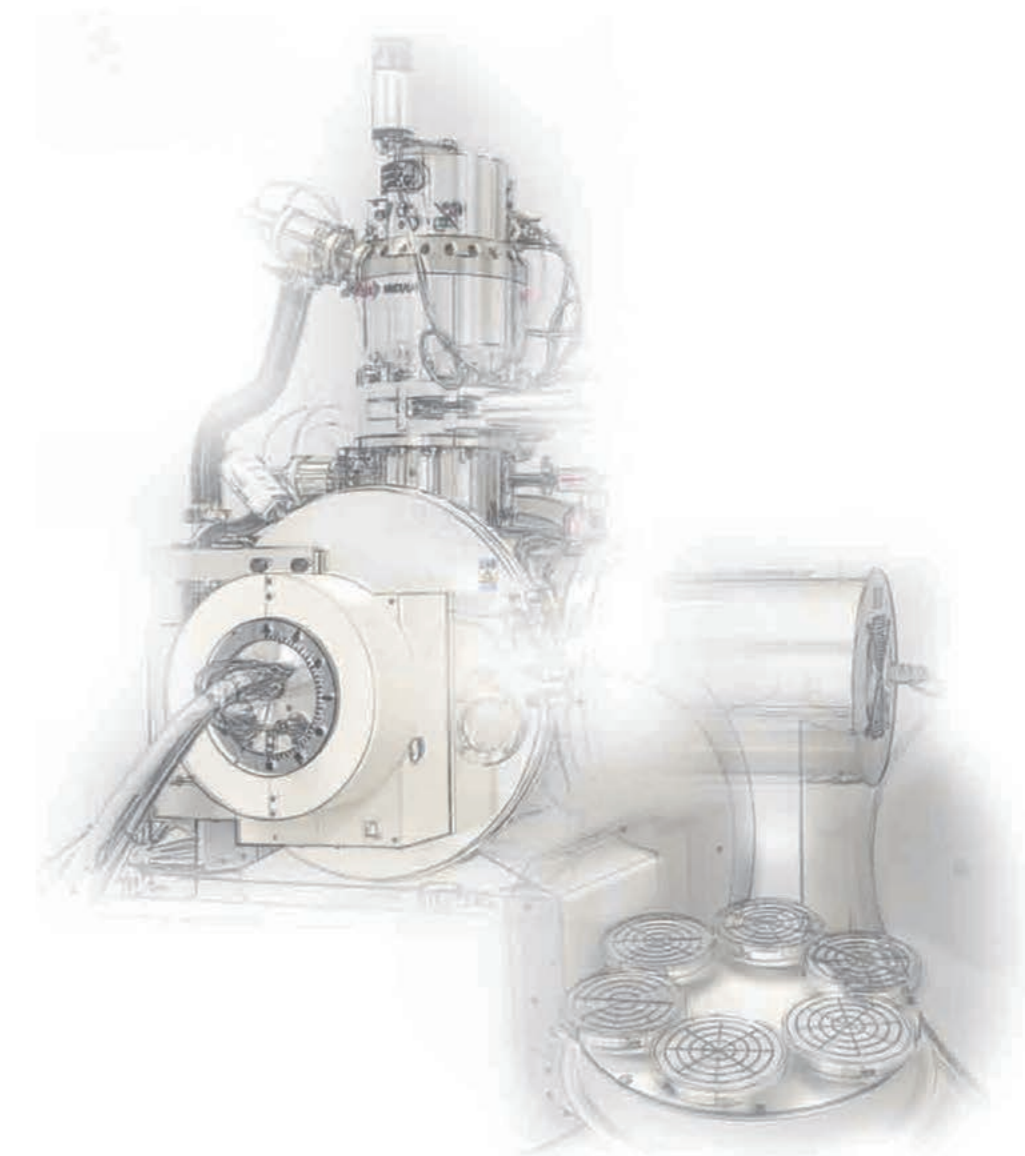


Ion Beam Milling System



Contact Us
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Ion Beam Milling System



Ion Beam Milling System

Contact us for Standard or Customized system with unique requirement.

From small scale system for R&D to large scale for production, we develop and offer "only one" system based on customer's requirement.

For any Ion Beam Milling(Etching) System inquiry, please contact Hakuto.

As a micro fabrication method, Ion beam milling system is adopted to wide variety of applications such as RF devices, Sensors, Magnetic devices for R&D and mass production. Difficult-to- Etch materials (Au, Pt, Magnetic material, thin metal multi layers) can be easily processed by physical etching process (no reactive chemical).

■ Features of ion beam milling equipment

• Planetary Stage

Planetary stage is employed in all type of systems for production. Thanks to planetary movement of stage and wafer holder, excellent milling uniformity is achieved.

• Direct Cooling or Indirect Cooling Stage

Direct cooling circulates cooling wafer inside wafer holder for excellent cooling performance. Indirect cooling enables the change of size and number of wafer holder easily.

• Dry Chuck

Wafer chuck with Dry Chuck Rubber incorporating metal powder ensures a good thermal conductivity and wafer attachment. Suitable rubber is available depending on the material of a sample.

• Design Freedom

We respond to customer's specific requirement as completely as possible in designing of system and offer custom-designed ion beam milling system.

For R&D · Small Chamber

10IBE



φ2" single stage

■ Features

- Suitable for R&D. Small foot print
- 4cm/8cm/10cm/16cm Kaufman type ion source applicable
- Wafer size x number : Up to φ8" x 1wfr
- Sample that is other than the shape of wafer is mountable with adaptor
- End point detector (optional) for precise ending of etching



End point detector

For R&D/Production, Medium Chamber

20IBE-C



φ4" x 6wfr Planetary Stage

■ Features

- Applied in a wide range from R&D to production
- 20m Kaufman type ion source equipped
- Wafer size x number : φ3" x 8wfr, φ4" x 6wfr etc...
- Planetary movement achieves excellent milling uniformity

For Production · Large Chamber

20IBE-J



φ4" x 12wfr Planetary Stage

■ Features

- Having enough processing capacity in a batch
- 20m Kaufman type ion source equipped
- Wafer size x number : φ4" x 12wfr, φ5" x 10wfr, φ6" x 8wfr etc...
- Planetary movement achieves excellent milling uniformity



伯东企业（上海）有限公司
HAKUTO ENTERPRISES (SHANGHAI) LTD.
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伯东公司在国内主要城市：上海，北京，苏州，广州，深圳，成都及厦门设有营业据点。

上海伯东真空产品事业部已累计为超过 10,000 家企业提供真空服务

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现货交期快：部分产品有现货，下单立即发货（现货数量有限，实际情况请联系销售工程师）

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